

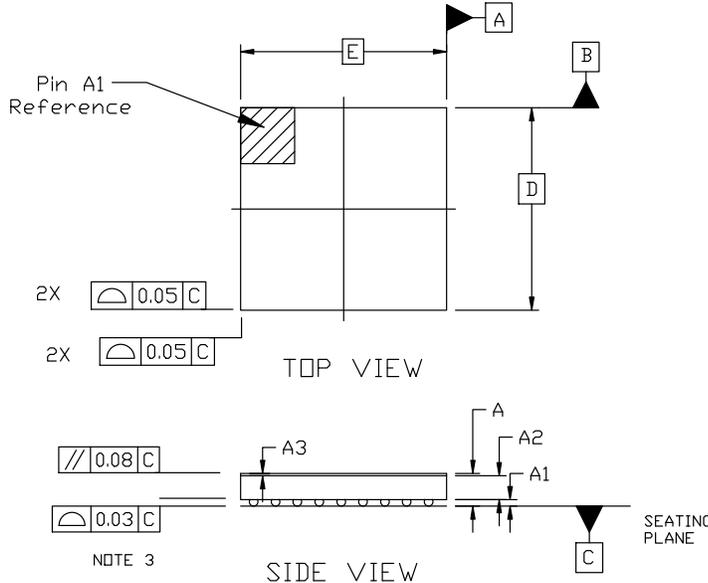
**WLCSP51, 2.364x2.325**  
**CASE 567MT**  
**ISSUE B**

DATE 19 MAY 2023

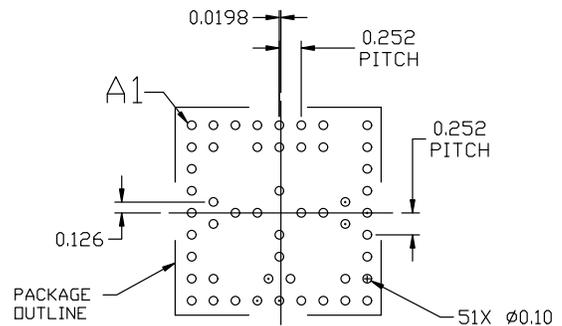
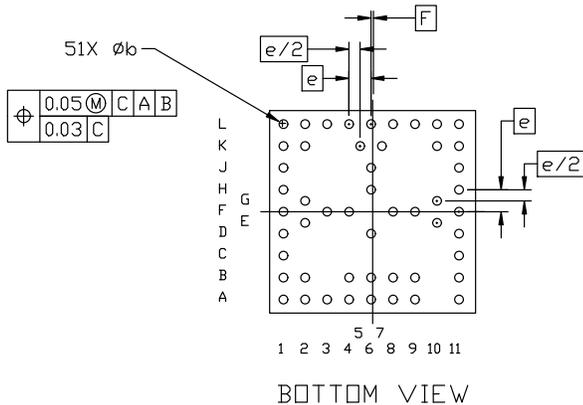
SCALE 4:1

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. PACKAGE CENTER AND FOOTPRINT CENTER ARE NOT COINCIDENT. REFER TO DIMENSION "F" FOR OFFSET.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.319	0.350	0.381
A1	0.060	0.075	0.090
A2	0.237	0.250	0.263
A3	0.022	0.025	0.028
b	0.09	0.10	0.12
D	2.325 BSC		
E	2.364 BSC		
e	0.252 BSC		
F	0.0198 BSC		



**GENERIC MARKING DIAGRAM\***



XXXXXX = Specific Device Code  
 A = Assembly Location  
 WL = Wafer Lot  
 YY = Year  
 WW = Work Week  
 ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP51, 2.364X2.325</b>	<b>PAGE 1 OF 1</b>

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